

No. : HEMCG0-1382 Date : April 30, 2012

MLCC: Monolithic Ceramic Capacitor

Notification - Discontinuance of Product

Dear Valued Customer,

Thank you very much for your patronage on our ceramic capacitor.

We would like to submit this letter to inform you about the discontinuance of some of our products.

1. Object Part

MLCC (Chip Monolithic Ceramic Capacitor):

GRx03 - GRx55 series (0.6×0.3mm - 5.7×5.0mm)

 $GCx03 - GCx55 \ series \ (0.6 \times 0.3 mm - 5.7 \times 5.0 mm) \ \ Only \ High \ Dielectric \ Constant \ Type$

GNx series

2. Applied Part Numbers and Murata Product Types

(1) Customer Part Number: Please find enclosed Appendix(1).

(2)Murata Product Types:

 GRxxxx
 xx
 xxx
 x
 xxx
 <t

3. Reason

Precious metal's market price continues to increase and stays high.

Palladium price has posed a great impact on Murata's MLCC product.

In addition to this is the Chinese government's export control from 2010,

Rare Earth's procurement and purchase cost has influenced our production efficiency.

Murata has been expanding the products that uses base metal for inner electrode material as standard products.

The change of inner elecrode to base metal enables us to manage the risk from the influence of precious metal market in supply and cost.

We would appreciate if you could accept this change.

4. Discontinuance Schedule

Dead line of one shot last order : September 30, 2013

Date of discontinue production : March 31, 2014

Please return this form with your signature by September 28, 2012.

We would like to take action after your acceptance.

Please feel free to contact us, if you have any question or request on our proposal.

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5. Proposal of alternate product

We would like to propose the alternate product.

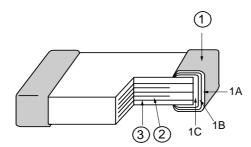
Please find enclosed Appendix(1).

Please confirm.

(1)Structure

· Fig.1 (Nickel Barriered termination)

· Fig.2 (Silver palladium termination)



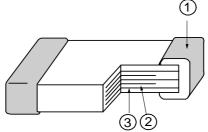


Table A : GRM/GCM TC PEM⇒GRM/GCM TC NEM

No.		NAME	Material	
			Current (Fig.1)	New (Fig.1)
1		Termination		
	1A	Plated layer	Tin	Tin
	1B	Plated layer	Nickel	Nickel
	1C	Electrode	Silver/Palladium or Silver	Copper
2		Dielectric layer	TiO2	CaZrO3
3		Inner electrode	Palladium or Silver/Palladium	Nickel

Table B : GRM/GCM Hik PFM⇒GRM/GCM Hik NFM

No.		NAME	Material	
			Current (Fig.1)	New (Fig.1)
1		Termination		
	1A	Plated layer	Tin	Tin
	1B	Plated layer	Nickel	Nickel
	1C	Electrode	Silver/Palladium or Silver	Copper
2		Dielectric layer	BaTiO3	BaTiO3
3		Inner electrode	Palladium or Silver/Palladium	Nickel

Table C: GRG/GRS/GCG/GCS Hik PEM⇒GRM/GCM Hik NEM

No.		NAME	Material	
			Current (Fig.2)	New (Fig.1)
1		Termination	Silver/Palladium or Silver	
	1A	Plated layer	-	Tin
	1B	Plated layer	-	Nickel
	1C	Electrode	-	Copper
2		Dielectric layer	BaTiO3	BaTiO3
3		Inner electrode	Palladium or Silver/Palladium	Nickel

(2) Please see attached Typical Reliability Test Data for your reference.

6. Others

This change will be applied to all Murata production factory of Chip MLCC, as follows. Fukui Murata Mfg.Co.,Ltd., Izumo Murata Mfg.Co.,Ltd., Okayama Murata Mfg.Co.,Ltd. Murata Electronics Singapore(Pte.)Ltd., Wuxi Murata Electronics Co.,Ltd.

Yours very truly,

The notification for the acceptance

Date :
Company :
Signature :
Comment :

Business Development Support Sec. I Planning & Market Promotion Department Monolithic Ceramic Capacitor Group Fukui Murata Mfg. Co., Ltd.

K. Makida

* Please return this form with your signature to our sales representative by September 28, 2012.